

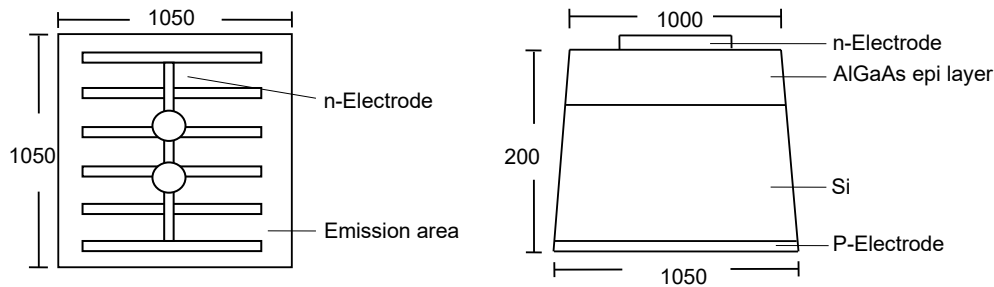
### ■ Features :

- Suitable for New Creative Products
- High Power
- High Performance
- Superior Thermal Stability

### ■ Typical Applications :

- Night Vision
- Camera
- Outdoor/Indoor applications

### ■ Outline Dimensions : (Unit: $\mu\text{m}$ )



### ■ Physical Structure :

LED Chip dimension	Chip size	1050 $\mu\text{m}$ x 1050 $\mu\text{m}$
	Thickness	200 $\pm$ 25 $\mu\text{m}$
	Emission area	1000 $\mu\text{m}$
	Bonding pad	130 $\pm$ 10 $\mu\text{m}$
Electrode	Top: N (cathode)	Gold
	Backside: P (anode)	Gold

\*C2

### ■ Electro-Optical Characteristics : ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	$V_{FH}$	$I_F = 350 \text{ mA}$	1.50	-	1.80	V
Reverse Current	$I_R$	$V_R = 5 \text{ V}$	-	-	1	$\mu\text{A}$
Radiant Power	$P_o$	$I_F = 350 \text{ mA}$	80	-	130	mW
Wavelength	$\lambda_P$	$I_F = 350 \text{ mA}$	870	-	900	nm
Spectral width at half height	$\Delta \lambda$	$I_F = 350 \text{ mA}$	-	30	-	nm

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

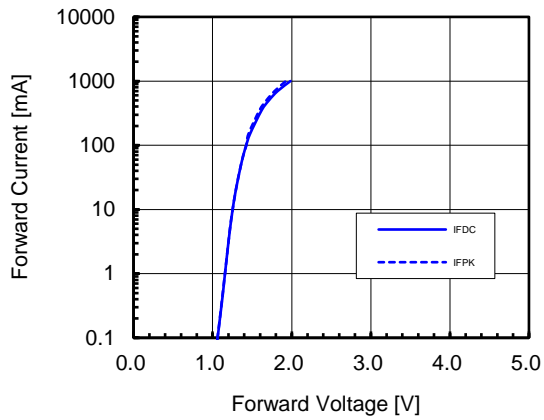


Fig 2. Relative Radiant Power vs. Wavelength

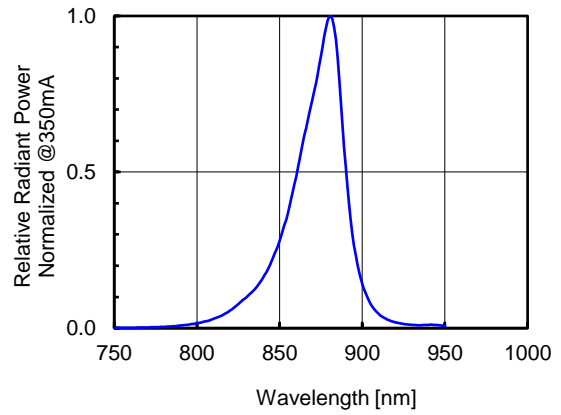


Fig 3. Relative Radiant Power vs. Forward DC Current

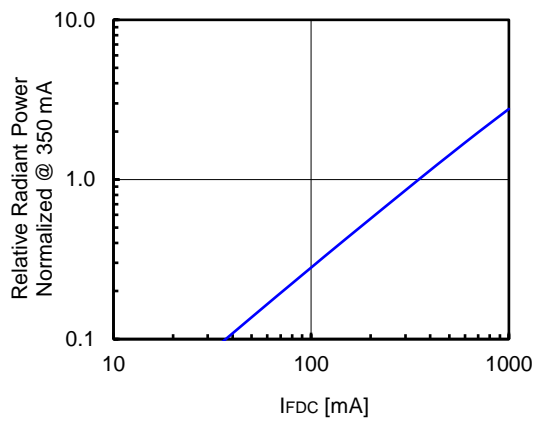


Fig 4. Relative Radiant Power vs. Forward Peak Current

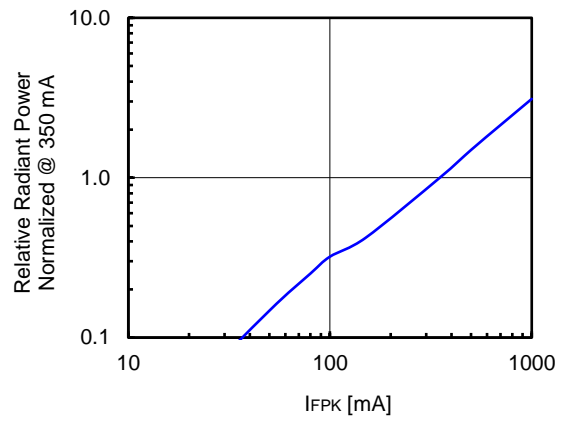


Fig 5. Forward DC Voltage vs. Temperature

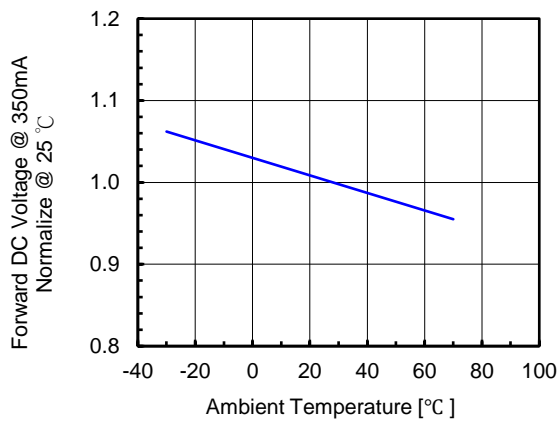


Fig 6. Relative Radiant Power vs. Temperature

